



Material Content Data Sheet



Sales Product Name		BTS50080-1TMA		Issued		19. January 2018		
MA#		MA000394051						
Package		PG-TO220-7-4		Weight*		1526.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.466	0.69	0.69	6857	6857
leadframe	non noble metal	iron	7439-89-6	0.910	0.06		596	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179	
	non noble metal	copper	7440-50-8	909.052	59.54	59.62	595592	596368
wire	non noble metal	aluminium	7429-90-5	2.541	0.17	0.17	1665	1665
encapsulation	organic material	carbon black	1333-86-4	8.796	0.58		5763	
	plastics	epoxy resin	-	96.757	6.34		63393	
	inorganic material	silicondioxide	60676-86-0	480.852	31.50	38.42	315044	384200
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7921	7921
plating	non noble metal	nickel	7440-02-0	0.216	0.01		141	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	141
glue	plastics	Polyimide	26023-21-2	0.426	0.03	0.03	279	279
solder	noble metal	silver	7440-22-4	0.098	0.01		64	
	non noble metal	tin	7440-31-5	0.078	0.01		51	
	non noble metal	lead	7439-92-1	3.746	0.25	0.27	2454	2569
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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